

L Number	Hits	Search Text	DB	Time stamp
87	45	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3) and ((grey or gray) same (mask or reticle))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB DERWENT	2003/07/22 15:20
88	0	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3) and ((grey or gray) same (mask or reticle))) not us.pc.	DERWENT	2003/07/22 15:32
89	0	(430/314,323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))) not us.pc.	DERWENT	2003/07/22 15:32
90	26	(((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (photomask or mask or reticle)) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:34
91	3048	430/314,323-324.ccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:44
92	36	((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and ((microbeam or microplatform or microsupport or (suspend\$3 with microstructure))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:39
93	915	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314,323-324.ccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:40
94	18	resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:40
95	36	430/314,323-324.ccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:41
96	11	(resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PPGPUB; EPO; JPO; IBM TDB	2003/07/22 15:41

97	1	((resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))) and ((grey or gray) with mask)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:41
98	2	(resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 16:18
99	17	((slop\$3 or inclin\$3 or taper\$3) with (etch\$3)) and 430/320.ccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))) not (((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314,323-324.ccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)) not (430/314,323-324.ccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))) not ((resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3)))) ((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) and (etch\$3)) and ((grey or gray))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:43
-	830		USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/24 16:24

-		35	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB DERWENT	2003/07/22 15:19
-		0	((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not us.pc.	DERWENT	2003/07/22 15:32
-		0	(430/314,323-324.cccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))) not us.pc.	DERWENT	2003/07/22 15:32
-		2920	430/314,323-324.cccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) ("5962909") or ("5831266") or ("6130109") or ("6025951") or ("6201243") or ("20020043706").PN.	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB	2003/01/17 17:08
-		6	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB	2003/01/17 09:20
-		35	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB	2003/01/17 15:37
-		29	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) with (photomask or mask or reticle))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB	2003/01/17 15:37
-		58	((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB	2003/01/17 15:41
-		23	((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB USPAT; US_PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:33
-		2919	430/314,323-324.cccls. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:35
-		623	(mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.	USPAT; US_PGPUB; EPO; JPO; IBM_TDB	2003/01/18 11:46
-		26	((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))	USPAT; US_PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:36
-		884	(photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cccls.	USPAT; US_PGPUB	2003/01/18 13:38
-		827	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cccls.) not 430/314,323-324.cccls.	USPAT; US_PGPUB	2003/01/18 13:39

-	827	((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).ccls.) not 430/314,323-324.cccls.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:38
-	17	resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PGPUB	2003/07/22 15:39
-	6636	electroplat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)	USPAT; US-PGPUB	2003/01/20 15:35
-	34	430/314,323-324.cccls. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:40
-	440	(resist or photoresist) and (air adj bridge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/23 17:03
-	210	(resist or photoresist) same (air adj bridge)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/23 17:04
-	10	(resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:41
-	1	((resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))) and ((grey or gray) with mask)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:41
-	2	(resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:42
-	900	(resist or photoresist) and ((microplatform or suspend\$3) same (slop\$3 or inclin\$3 or taper\$3))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/01/24 11:20

	16	((slop\$3 or inclin\$3 or taper\$3) with (etch\$3)) and 430/320.cc1s.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (430/314,323-324.cc1s. not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not ((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))) not ((mems or moems or microelectromechanical or micro adj electromechanical).ti.ab.) and (microbeam or microplatform or microsupport or (suspend\$3 with microstructure))) not (((photolithograph\$6 or lithograph\$6 or photoresist or resist) and etch\$3 and (204/192.14-192.15,192.17,192.23,192.25 or 205/122-123,125).cc1s.) not 430/314,323-324.cc1s.) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (mask or reticle))) not (resistive adj evaporat\$3 and ((photolithograph\$6 or photoresist or resist) same etch\$3)) not (430/314,323-324.cc1s. and (planarization adj layer) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not ((((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) same (etch\$3)) and ((grey or gray) same (photomask or mask or reticle))) not (((resist or photoresist) and (slop\$3 or inclin\$3 or taper\$3)) with (etch\$3)) and ((grey or gray) same (photomask or mask or reticle)))) not ((resist or photoresist) and (air adj bridge same (slop\$3 or inclin\$3 or taper\$3))) not ((resist or photoresist) and ((microbeam) same (slop\$3 or inclin\$3 or taper\$3)))	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2003/07/22 15:42
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